

# Topics

- ILC situation
  - Pedestal
  - MIP
- 
- Preparation of next TB

# ILC situation now

- Energy fixed to 250 GeV (previously 500 GeV)
  - ~5000 Oku-yen, with 50-60% from Japan
  - Approved by ICFA last year
- “Green light” or start international negotiations necessary in this year to survive
  - European strategy input deadline, 18 Dec. 2018
- MEXT advisory committee finished
  - Scientific merits are recognized
  - Costing issue and understanding from general public
- Re-evaluation by SCJ (日本学術会議) started

# SCJ evaluation

- Previous SCJ evaluation at 2013
  - Too early for decision
    - MEXT review panel activated
- Members: non-HEP researchers
  - Astrophysics, nuclear physics
  - Material science
  - Engineering, biology, philosophy
- Intensive evaluation from August
  - Two committees meet ~ every week
- Will conclude in Sep-Oct
  - if positive, statement of government at Nov-Dec?

## I L C見直し案検討委のメンバー 【検討委】

小林 伝司（大阪大副学長、哲学）  
西條 辰義（高知工科大教授、経済学・環境学）  
梶田 隆章（東京大教授、物理学）  
田村 裕和（東北大院教授、物理学）  
米田 雅子（慶応大特任教授、土木工学・建築学）  
家 泰弘（日本学術振興会理事、物理学）  
上坂 充（東京大院教授、総合工学・物理学）  
杉山 直（名古屋大院教授、物理学）  
永江 知文（京都大院教授、物理学）  
平野 俊夫（量子科学技術研究機構理事長、基礎医学）

## 【分科会】

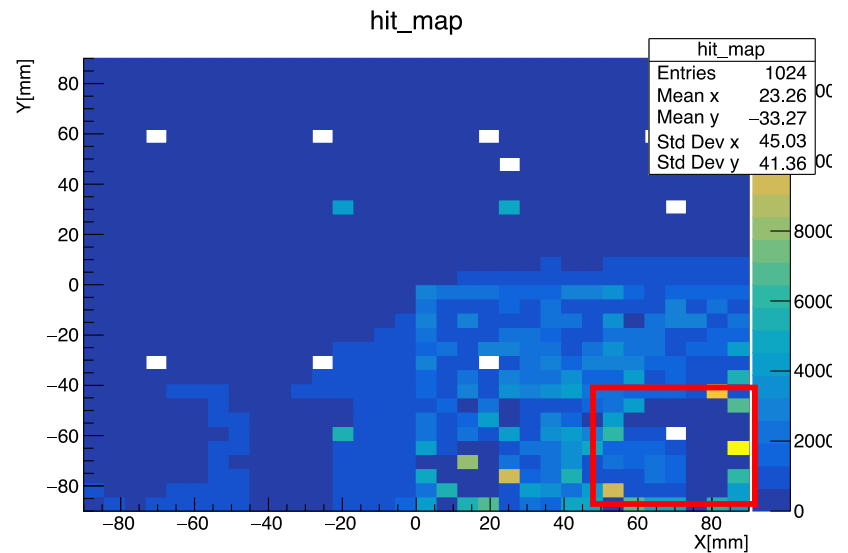
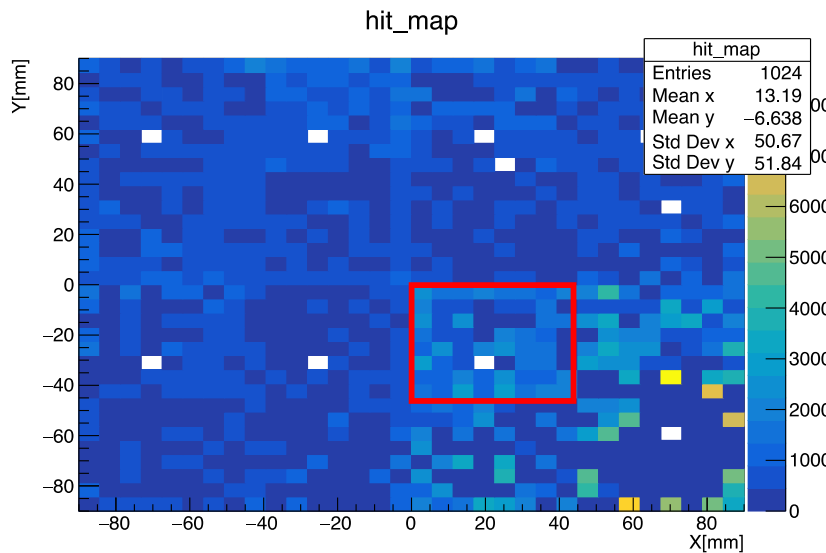
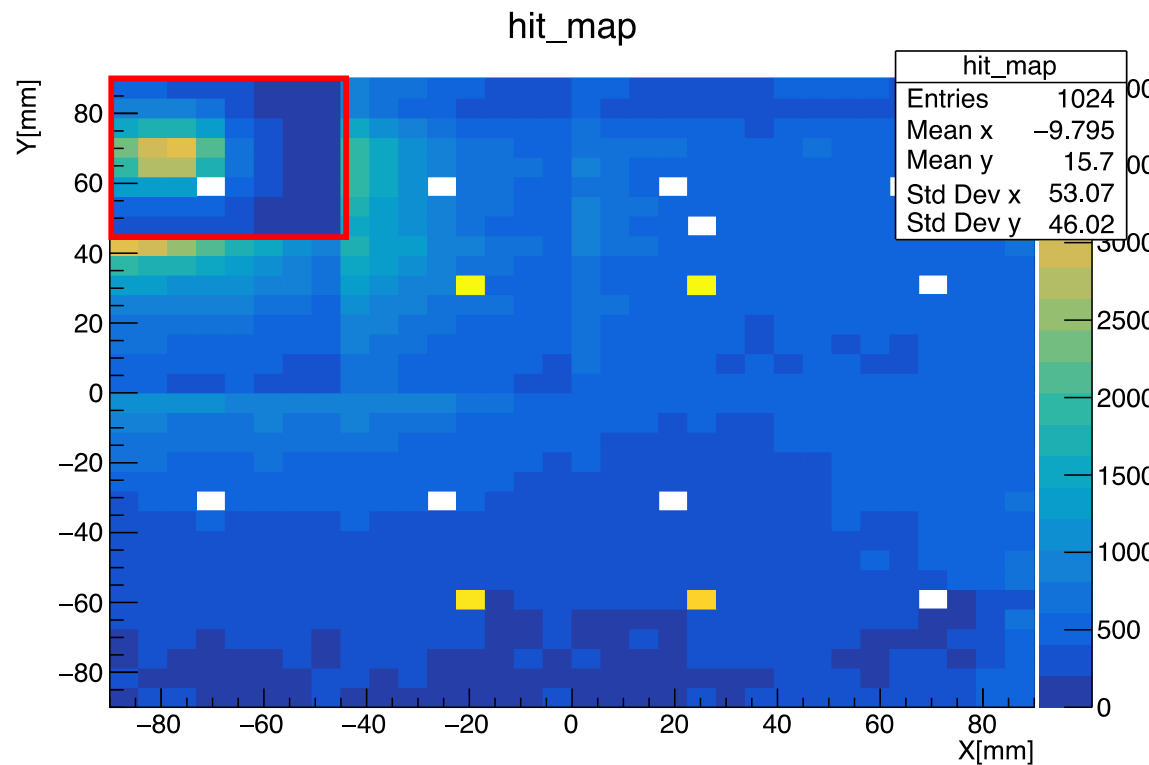
嘉門 雅史（京都大名誉教授、土木工学・建築学・環境学）  
中静 透（総合地球環境学研究所特任教授、基礎生物学）  
望月 常好（経済調査会理事長、土木工学・建築学）  
田中 均（理化学研究所放射光科学総研副センター長）  
※検討委の西條辰義、米田雅子、家泰弘の3氏も分科会

# 解析結果

- Hit Map

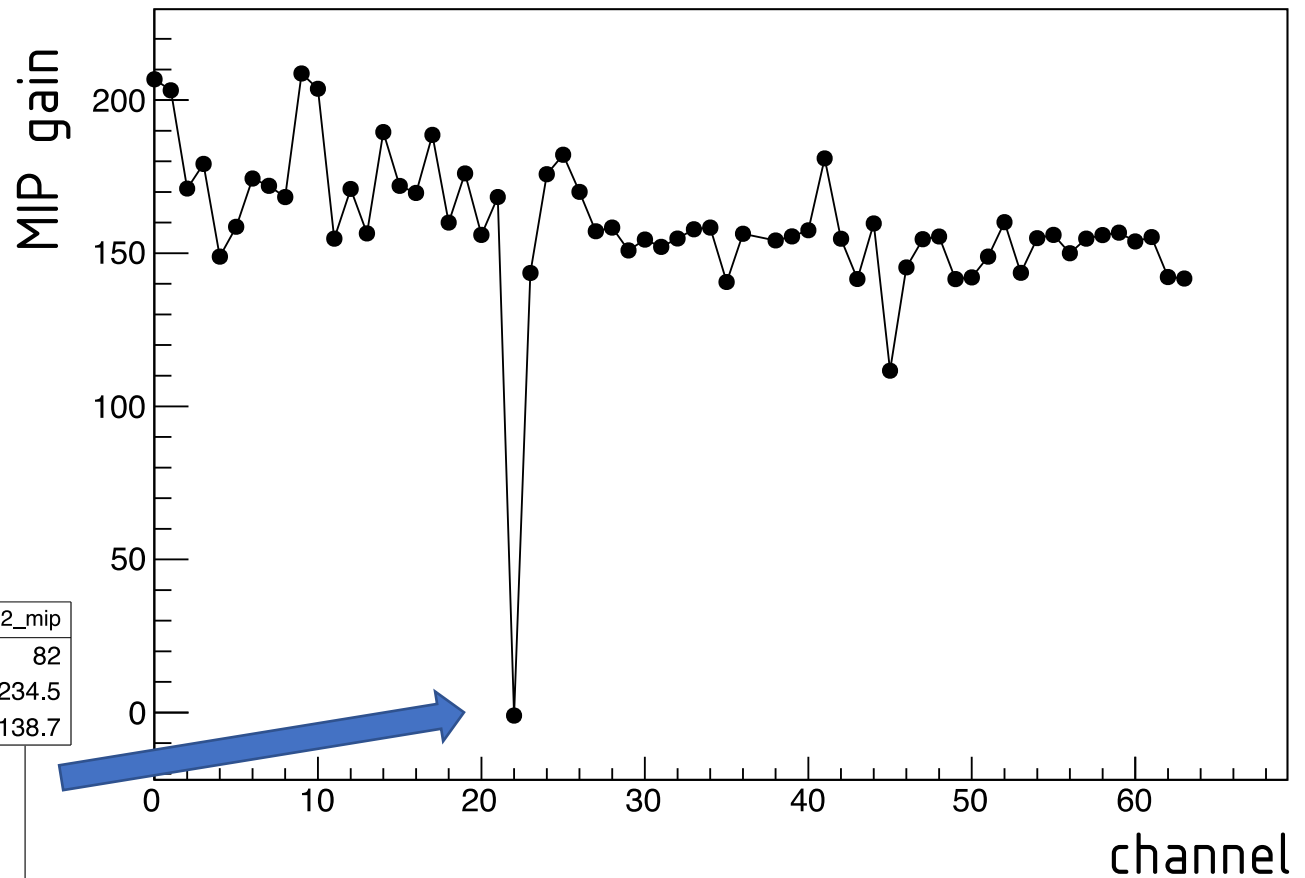
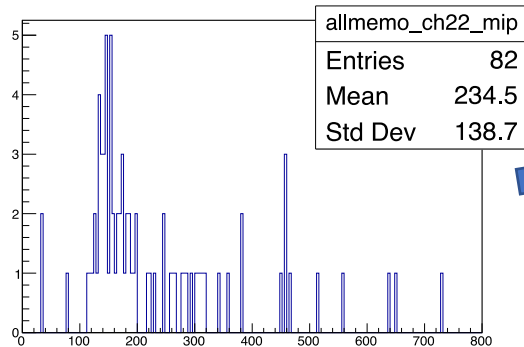
Hit map at the left-top chip clearly shows the beam

Hit map on the right-bottom sensor is not clear



# 解析結果

- gain mean

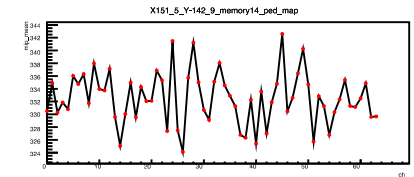
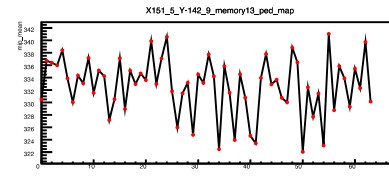
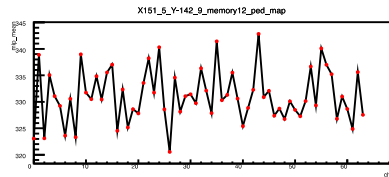
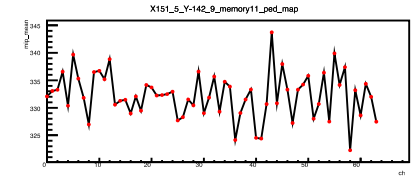
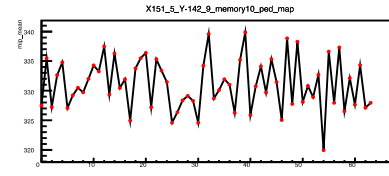
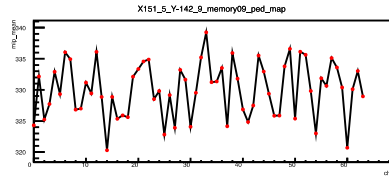
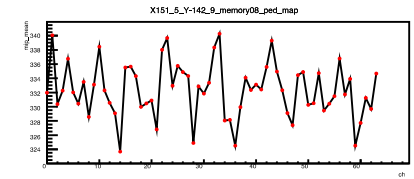
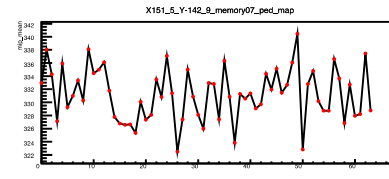
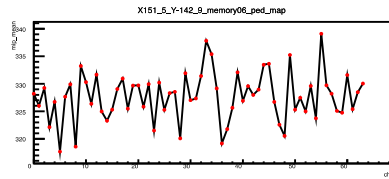
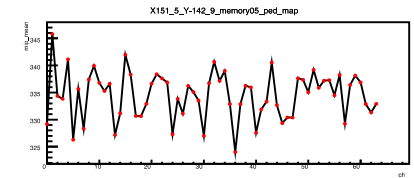
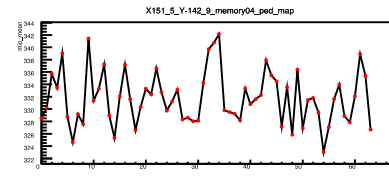
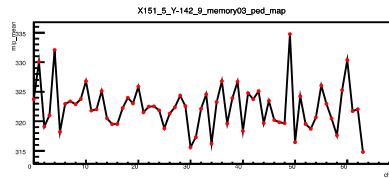
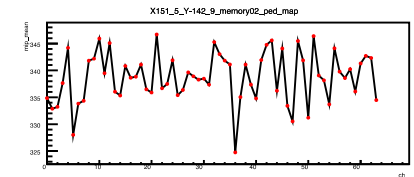
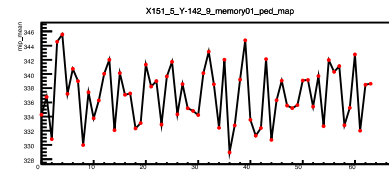
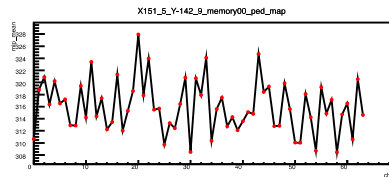


- Average: around 170
- Lower mean for higher channel
- Fit failure on ch 22, with different fitting range  
it gives 174.3

# 解析結果

- pedestal mean

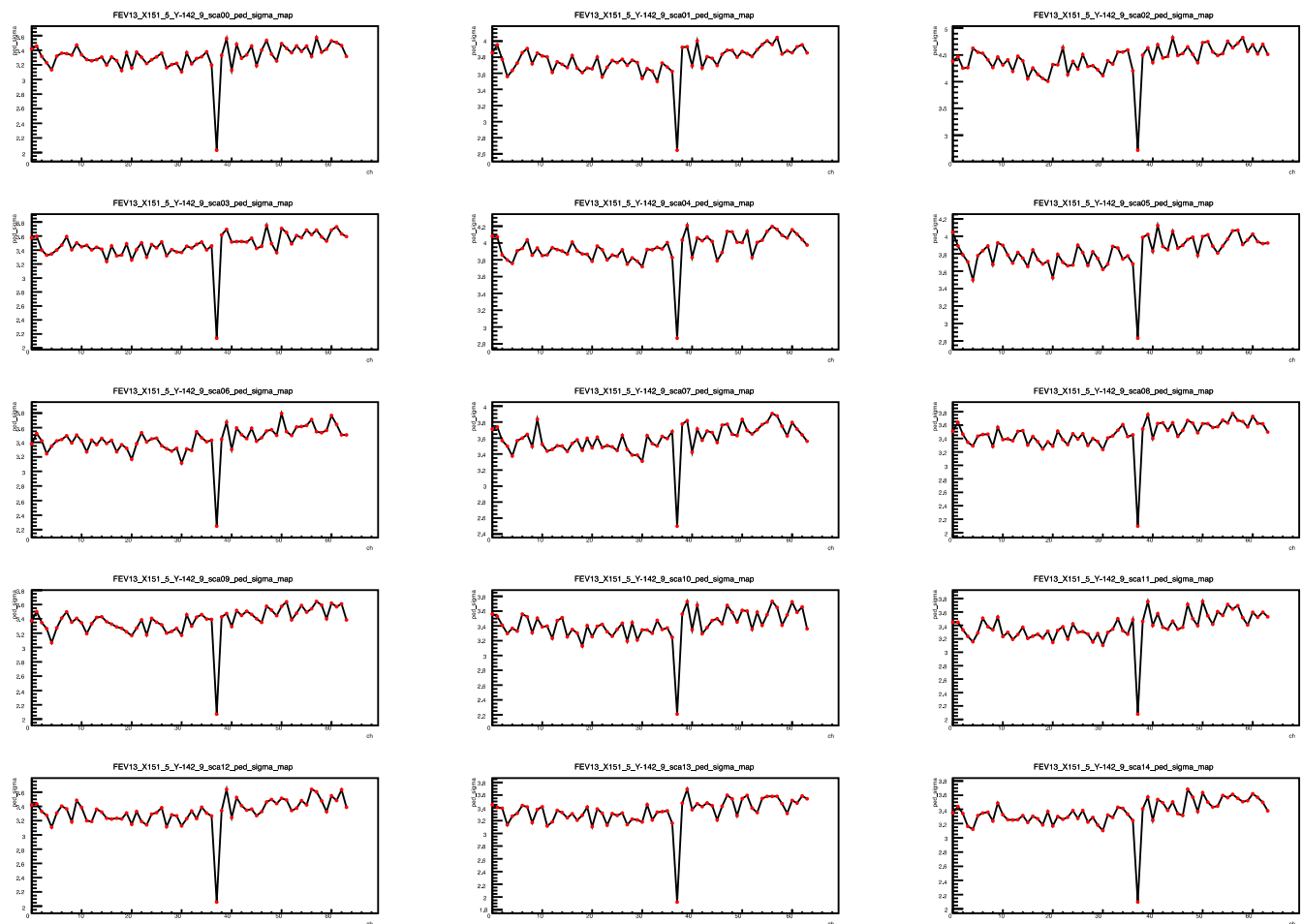
各ch,memoryに  
おける、mean  
をプロットした  
もの



- average: 320-340
- mean on memory 0 is smaller
- We see both inter-memory and inter-channel correlation (inter-channel correlation is larger)

# 解析結果

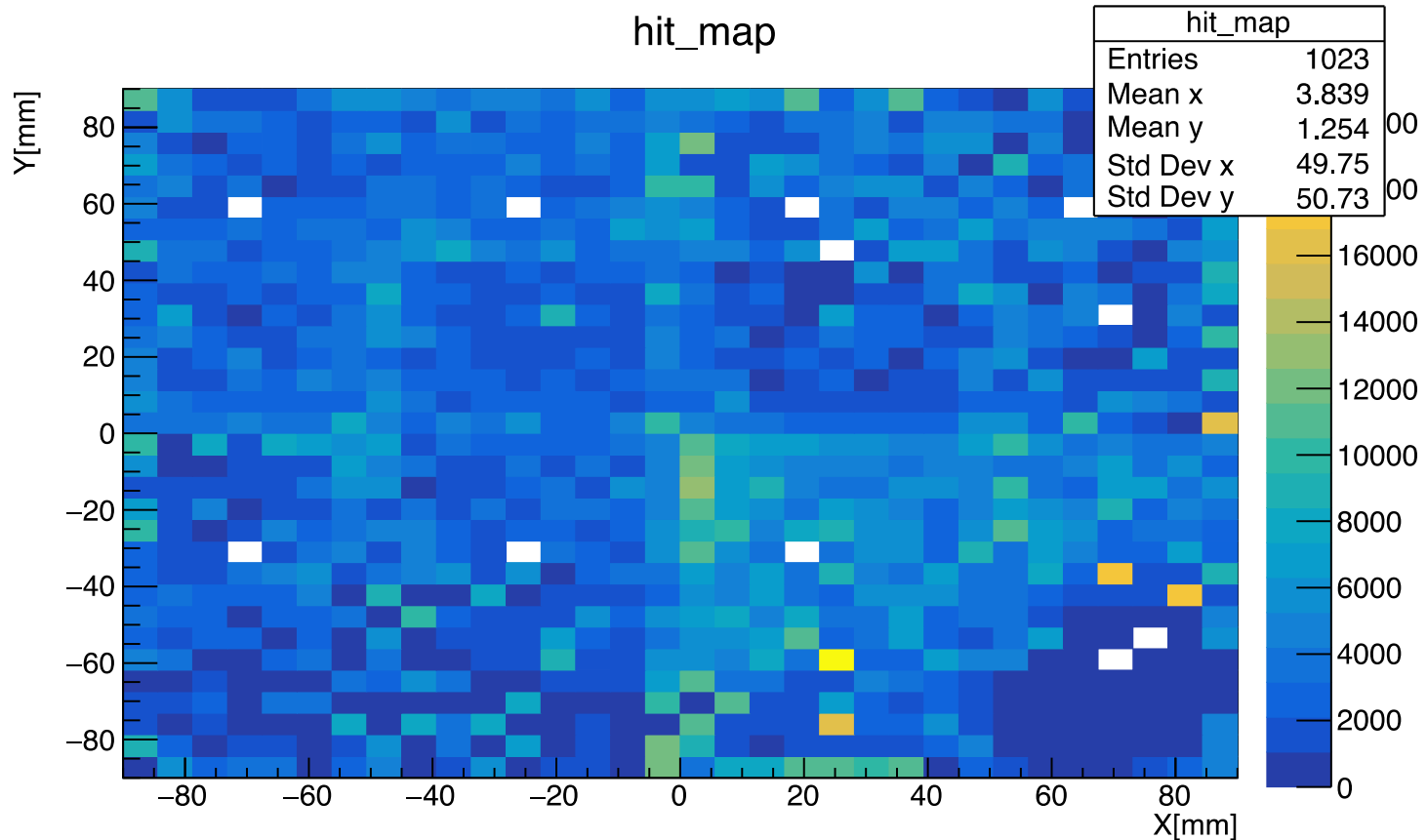
- pedestal sigma



- sigma is 3.0-4.0
- Inter-channel correlation is larger
- Inter-memory correlation is smaller

# 解析結果

- Hit Map (W shower)

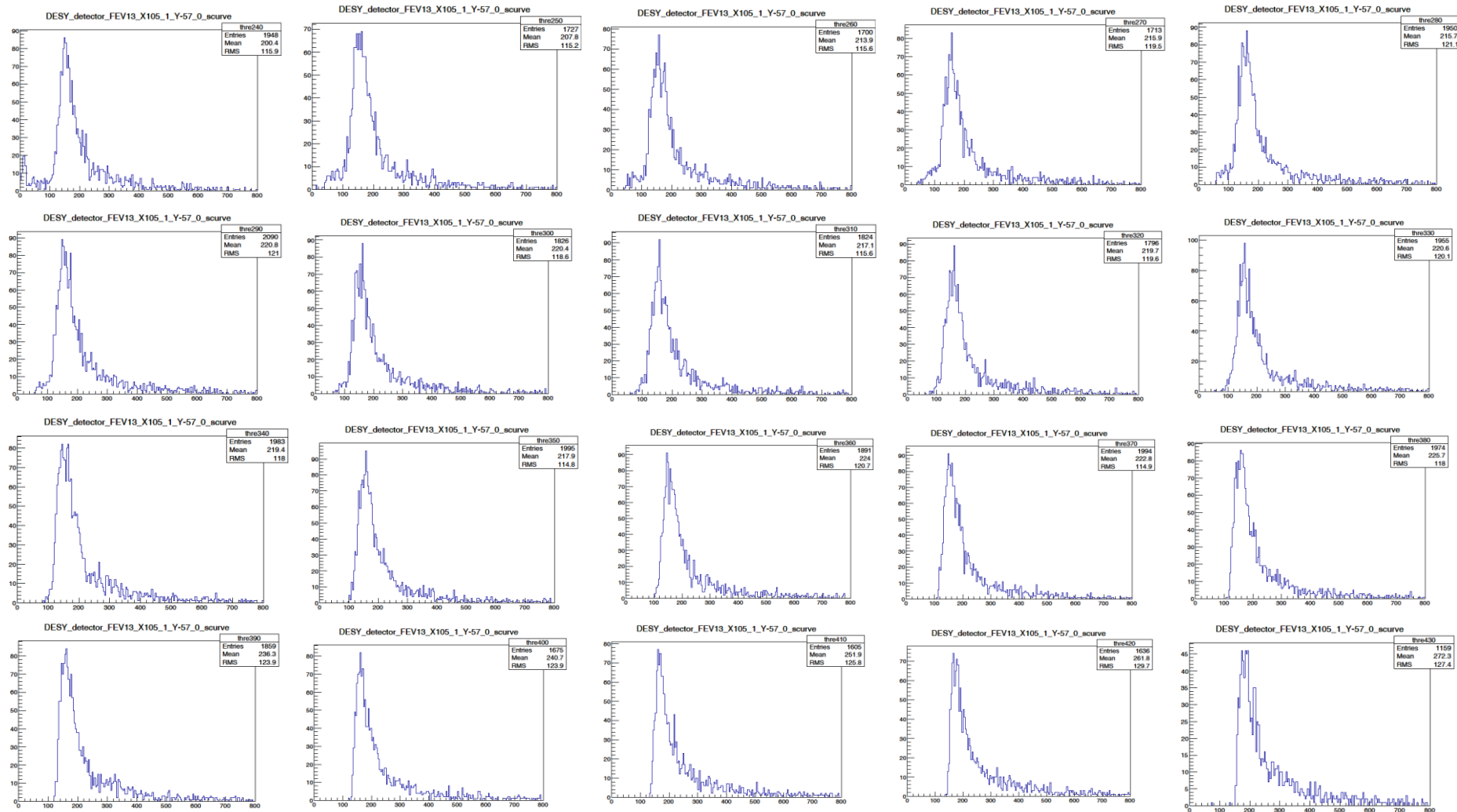


- Hit position is not clear
- Should check the effect of noise



# scurves

- I analyzed a position of chip10.
- A pedestal was subtracted every memory and then the histograms generated were added over all memories and channels.
- The thresholds was 240, 250,  $\dots$ , 430.
- Data directory  
home/data/DESY2018\_TB21\_v2/DESY\_detector\_FEV13\_X10  
5\_1\_Y-57\_0/20180707\_210651/scurves\_1.0Hz\_3.0ms/0/



# A slab

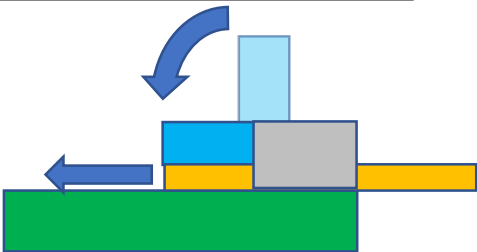


# short slab

- We will prepare 5 short slabs

FEV number		# A	#B	#C	#D	#0
Connector between FEV & SMB		P	P	P	K	K
Voltage application		Flexible board				
Sensor type (thickness: mm)		650	650	320	650	650
Date of gluing	FEV & sensor	31 Aug.	3 Sep.	6 Sep.	5 Sep.	15 Jun. → 5 Sep.
	flexible & SMB & FEV	4 Sep.	5 Sep.	7 Sep.	6 Sep.	6 Sep.

P type connector

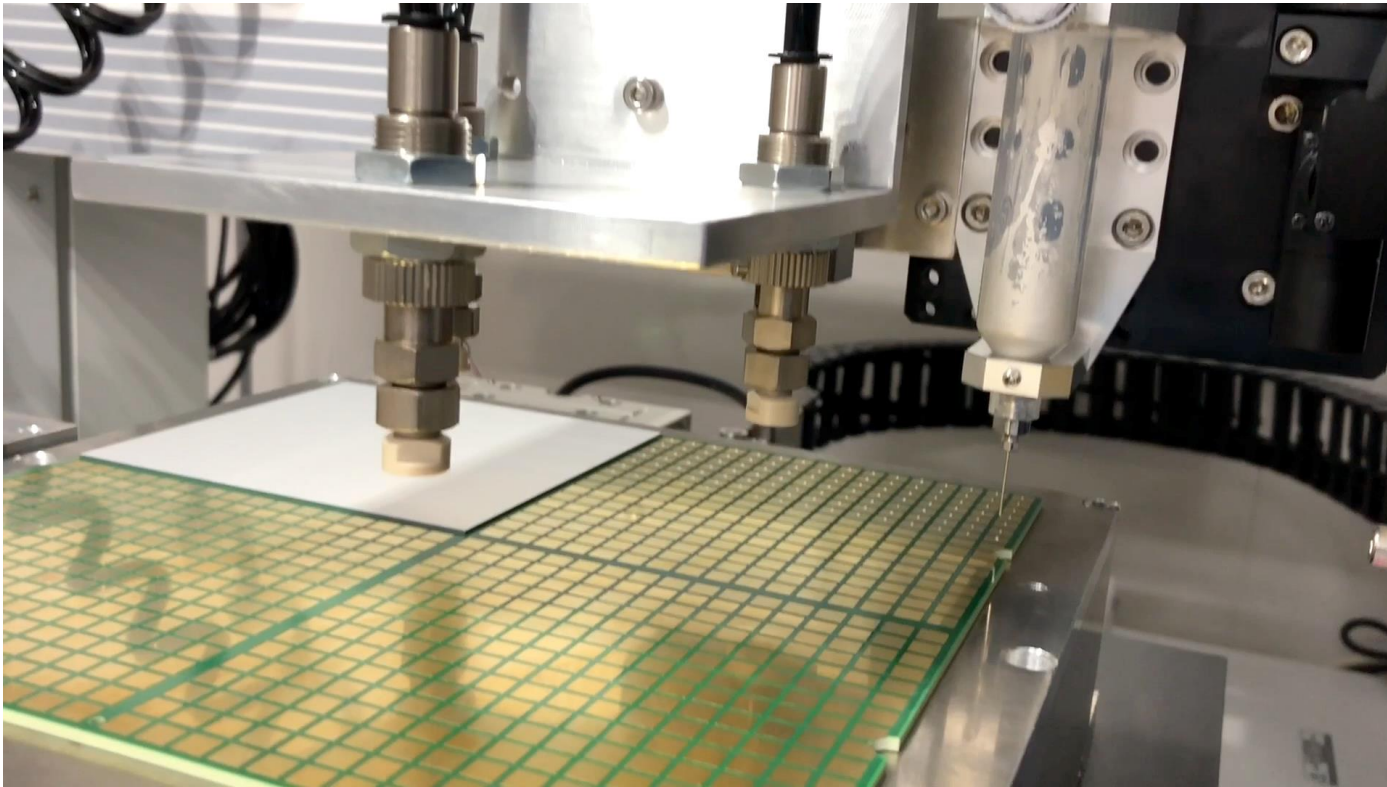


K type connector



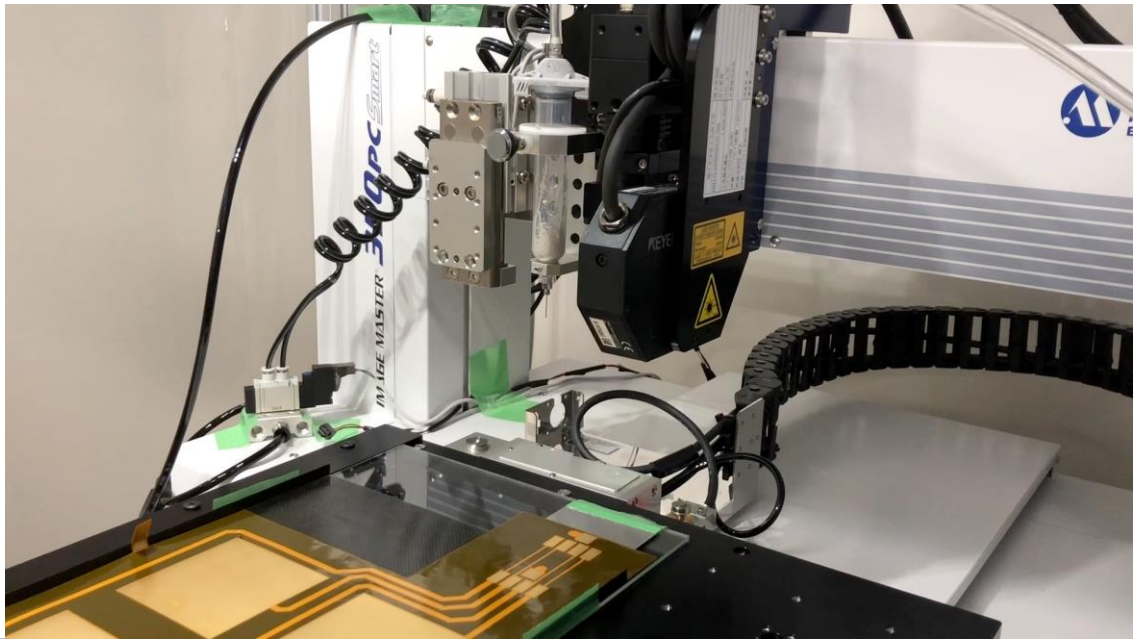
# Automation of gluing for #A, B

Auto	Object	Parameters
Stage	Jigs for sensor & FEV	Y-axis
Robot arm	Pads for sensor	X-axis, Z-axis
Vacuum generator	Fixing sensor Transporting sensor	ON/OFF
Dispenser	Gluing	Shooting time

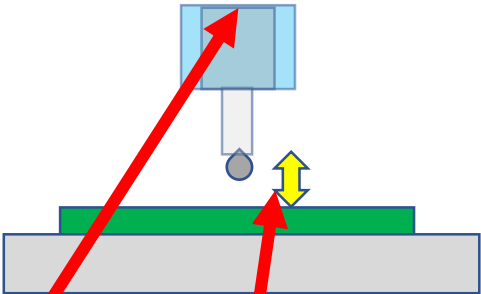


2 min  
30 sec

# Automation of gluing for flexible board



Movie : about 30 sec.



Auto	Object	Parameters
Stage	Jigs for sensor & FEV	Y-axis
Robot arm	Pads for sensor	X-axis Z-axis
Vacuum generator	Fixing sensor Transporting sensor	ON/OFF
Dispenser	Gluing	Shooting time
Image recognition device	Glue syringe	Height from FEV

# Summary

- We will prepare 5 short slabs

FEV number		# A	#B	#C	#D	#0
Connector between FEV & SMB		P	P	P	K	K
Voltage application		Flexible board				
Sensor type (thickness: mm)		650	650	320	650	650
Date of gluing	FEV & sensor	31 Aug.	3 Sep.	6 Sep.	5 Sep.	15 Jun. → 5 Sep.
	flexible & SMB & FEV	4 Sep.	5 Sep.	7 Sep.	6 Sep.	6 Sep.

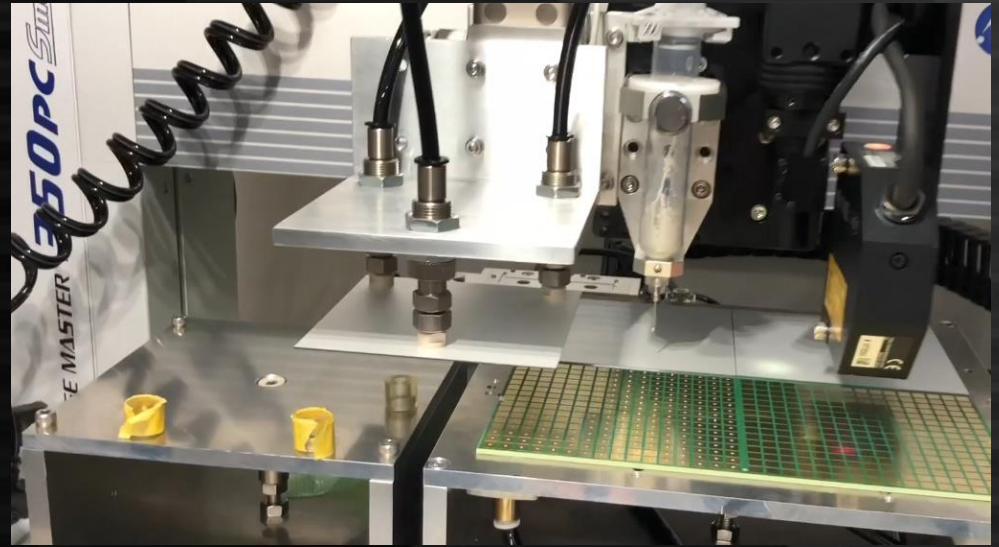
- Miura-kun will bring them to CERN and test them with beam



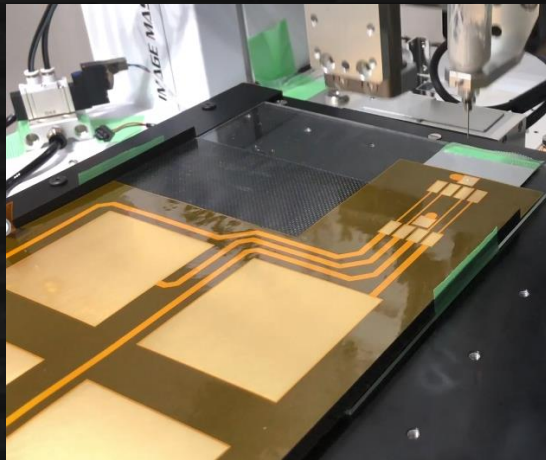
# Assembly procedure



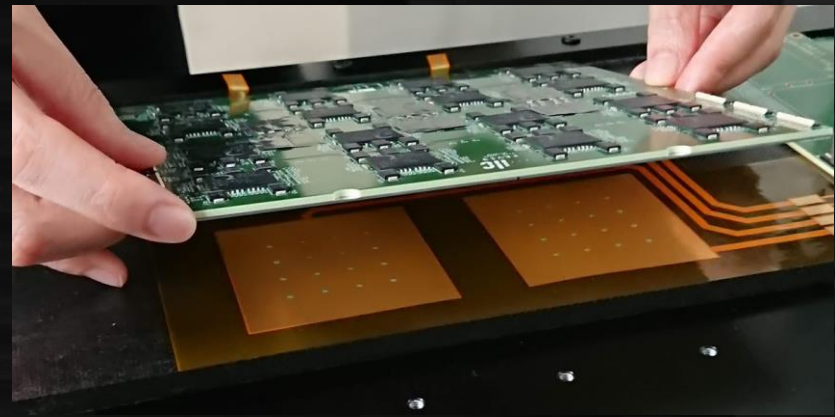
Dispense conductive glue



Place sensors → 1 day cure



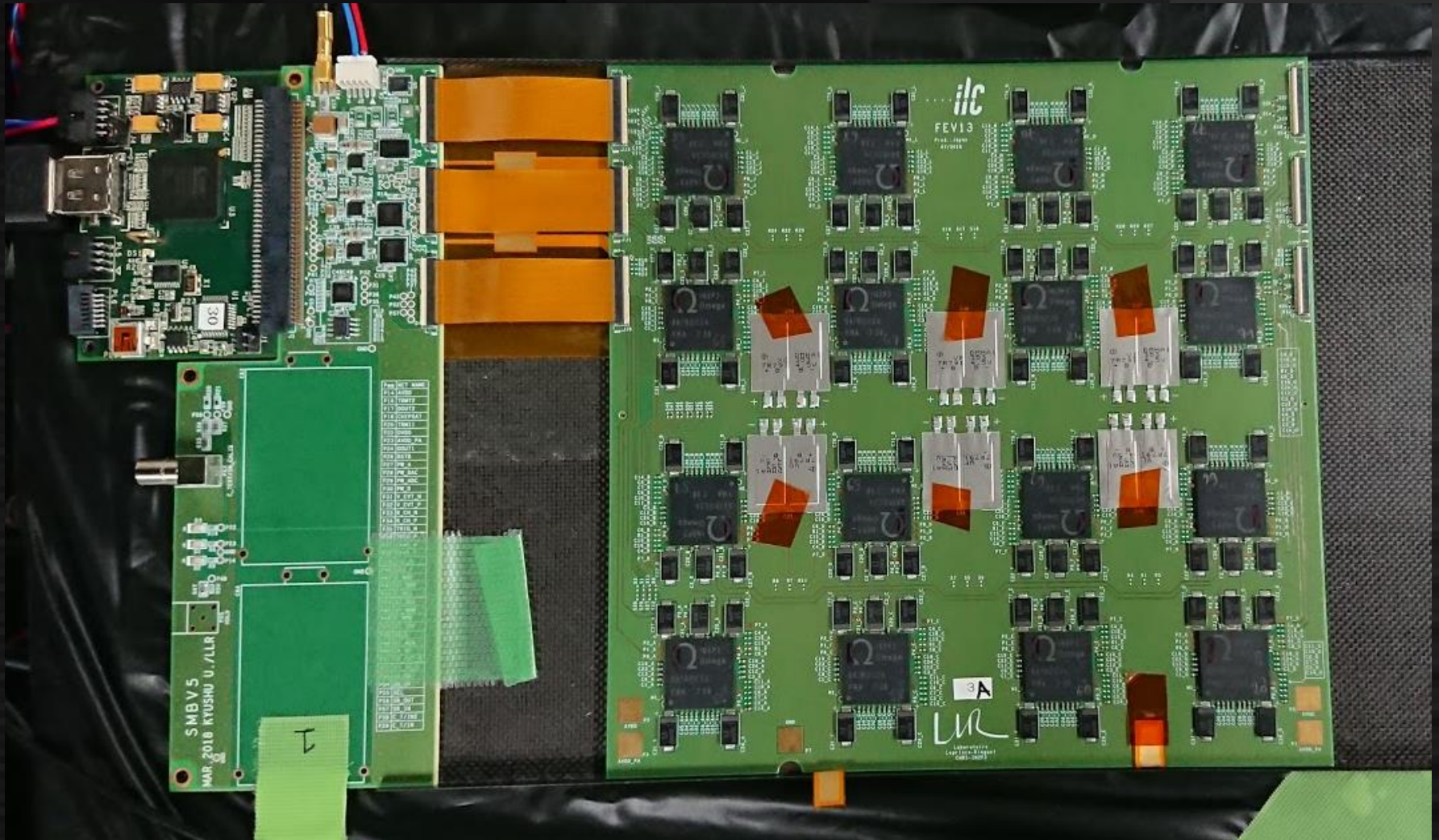
Dispense glue to flex



Mount sensor+PCB → 1 day cure



# First assembled FEV13JP





# Topics

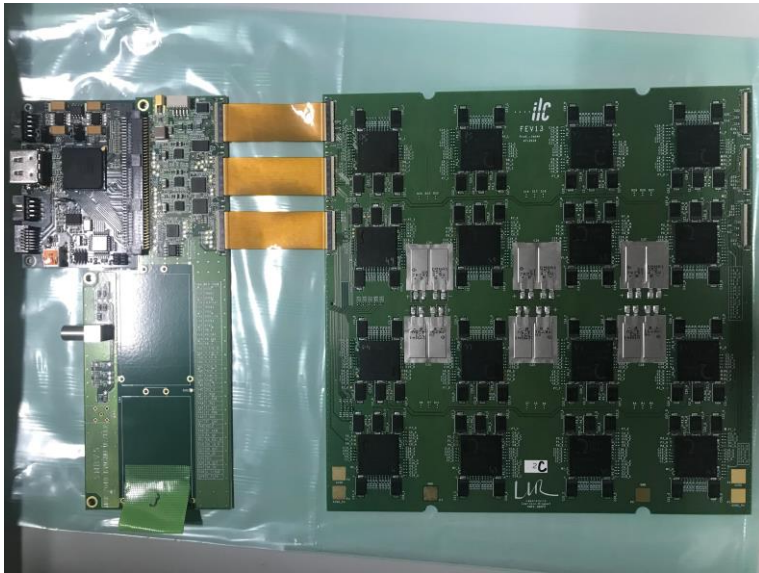
## ECAL-related activities

- Production of ECAL assembly
  - ASIC quality assurance (Deguchi)
  - Production of PCB and flexible boards (Suehara)
  - Gluing PCB-sensor-flex (Sekiya)
  - Test with  $^{57}\text{Co}$  (Miura)
  - Modification of FPGA (Miura)
- Test beam analysis (Uesugi)
- Test of new sensors (Mori)

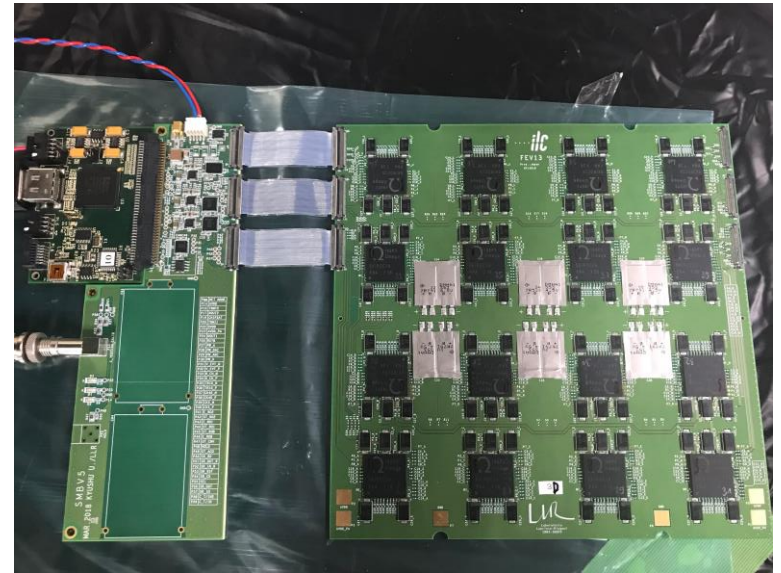
## Physics

- Two-fermion study (Deguchi)

# Test two types of FEV



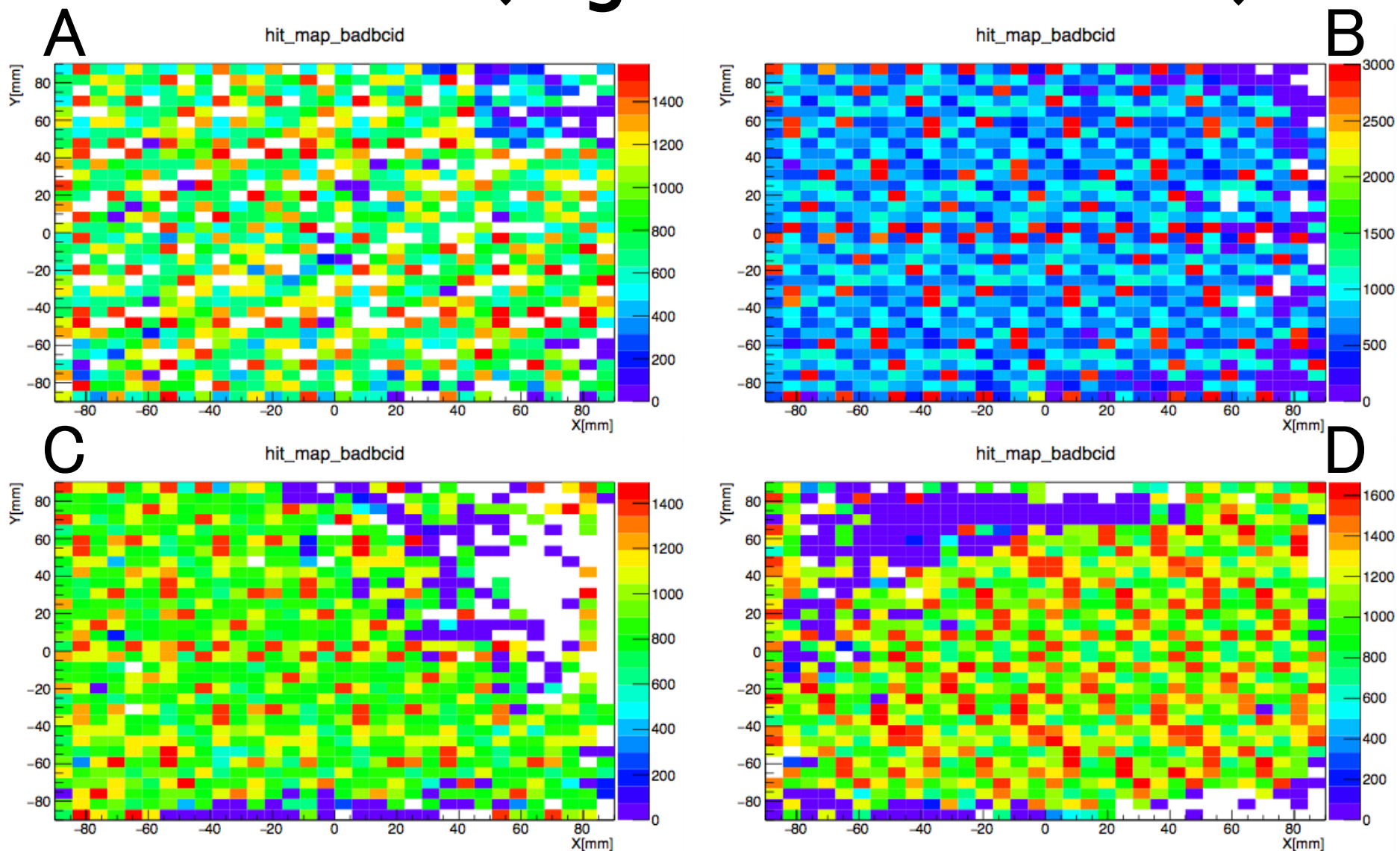
Type P



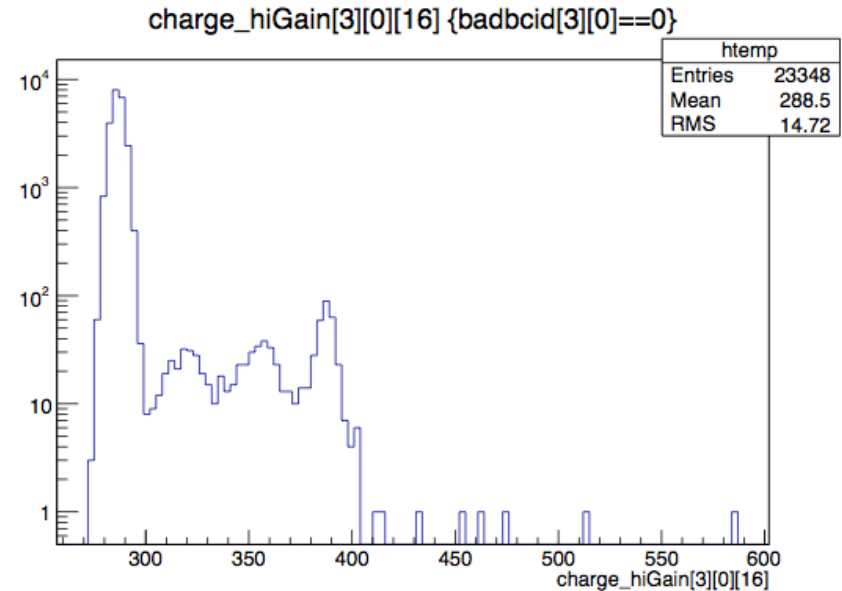
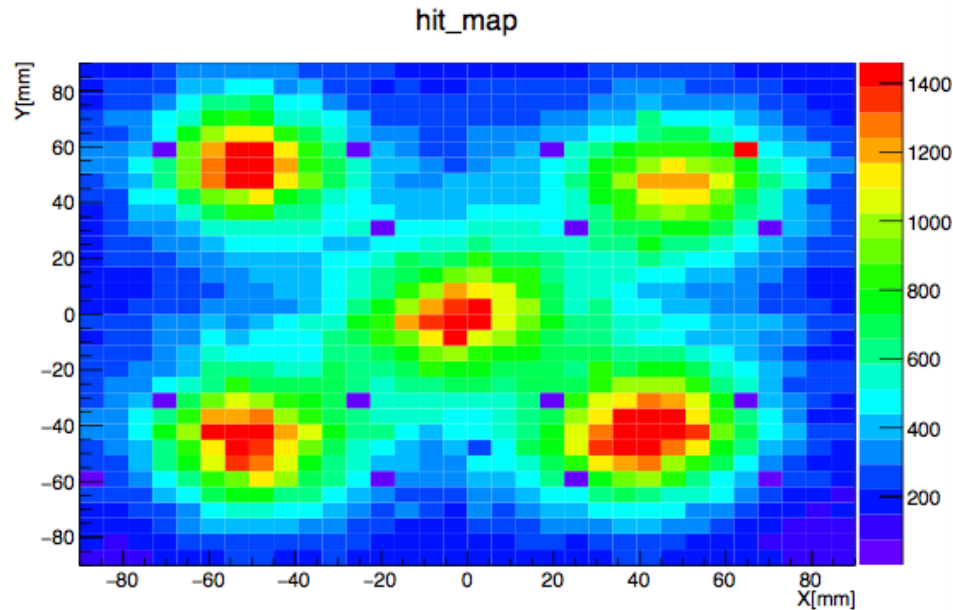
Type K

- We have two types of FEV. Connectors are different.
- Injected 10 MIPs at 50 kHz in 8 channels on 16 chips in 8 times (the chip have 64 channels)
- Use  $^{57}\text{Co}$  to confirm S/N ratio.

# Result (Inject 10 MIPs)



# Result ( $^{57}\text{Co}$ )



- We can get data now !  
But we have to finish to acquire datas in 4 times, because we have to test 5 SLABs. We already finished only the SLAB.
- S/N ratio is about 30.